

a second step in which pressure is applied between said semiconductor chip and said substrate, said interconnect pattern and said electrodes are electrically connected via said conductive particles of said adhesive, and said adhesive is caused to cover substantially all of a lateral surface of said semiconductor chip.

8. (Three Times Amended) A semiconductor device, comprising:  
a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive, said adhesive having conductive particles dispersed therein;  
wherein said electrodes and said interconnect pattern are electrically connected via said conductive particles of said adhesive; and  
wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

11. (Twice Amended) The semiconductor device as defined in claim 8, wherein said adhesive is provided to cover said interconnect pattern in its entirety.

12. (Amended) The semiconductor device as defined in claim 8,  
wherein said adhesive includes a shading material.

14. (Twice Amended) A circuit board on which is mounted a semiconductor device, the semiconductor device comprising:  
a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive, said adhesive having conductive particles dispersed therein;  
wherein said electrodes and said interconnect pattern are electrically connected via said conductive particles of said adhesive; and  
wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which

said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

15. (Twice Amended) An electronic instrument having a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive, said adhesive having conductive particles dispersed therein;

wherein said electrodes and said interconnect pattern are electrically connected via said conductive particles of said adhesive; and

wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

16. (Amended) The semiconductor device as defined in claim 8, wherein at least a part of said adhesive has a thickness substantially the same as said semiconductor chip.

#### REMARKS

Claims 1, 2, 5-8, 11, 12, 14-16, 21 and 22 are pending herein, with non-elected claims 1, 2 and 5-7 being withdrawn from consideration by way of a Restriction Requirement.

By this Amendment, claims 1, 8, 11, 12 and 14-16 are amended and claims 4 and 10 are canceled.

More in particular, each of independent claims 1, 8, 14 and 15 is amended to recite that the adhesive includes conductive particles dispersed therein, which conductive particles participate in the electrical connection between the electrodes and the interconnect pattern. The amended claims distinguish the claimed invention from the teachings of Yamada as discussed more fully below. Support for these amendments to the claims may be found throughout the original specification, including original claims 4 and 10.